

Overview

The purpose of this notification is to announce a change in Xilinx[®] Alveo[™] U200/U250 footprint pad improvement and firmware update. There is no change to the form, fit, function, or reliability.

Description

As part of Xilinx continuous improvement, the Alveo U200 and U250 footprint pads have been modified to improve the solder-joint for power supply components and provide additional margin for the temperature cycling stress tests beyond industry requirements.

The Alveo Satellite Controller firmware has been updated to support Out-Of-Band (OOB) access to FRU in EEPROM (reference to [UG1363](#) and [UG1378](#)) in Xilinx 2019.1 XDMA.

Products Affected

This change affects all Alveo U200 and U250 products. Any associated specification control document (SCD) versions of the standard part number are also affected.

Table 1: Alveo U200 and U250 Data Center Accelerator Cards

Part Number	Description
A-U200-A64G-PQ	Alveo U200 Data Center Accelerator Card (Active Cooling Card Option)
A-U200-P64G-PQ	Alveo U200 Data Center Accelerator Card (Passive Cooling Card Option)
A-U250-A64G-PQ	Alveo U250 Data Center Accelerator Card (Active Cooling Card Option)
A-U250-P64G-PQ	Alveo U250 Data Center Accelerator Card (Passive Cooling Card Option)

Key Dates and Ordering Information

Xilinx will begin shipping the updated Alveo U200 product (PCB revision 03) starting October 19, 2019.
Xilinx will begin shipping the updated Alveo U250 product (PCB revision 02) starting October 19, 2019.
Updated firmware may begin shipping with current Alveo U200 and U250 products upon this PCN release.

Qualification Data

Qualification data is available upon request.

Required Action

No response required.

Important Notice: Xilinx Customer Notifications (XCNs, XDNs, and Quality Alerts) can be delivered via e-mail alerts sent by the Support website (<http://www.xilinx.com/support>). Register today and personalize your “Documentation and Design Advisory Alerts” area to include Customer Notifications. Xilinx Support provides many benefits, including the ability to receive alerts for new and updated information about specific products, as well as alerts for other publications such as data sheets, errata, application notes, etc. For information on how to sign up, refer to [Xilinx Answer Record 18683](#).

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
08/26/2019	1.0	Initial release

Notice of Disclaimer

The information disclosed to you hereunder (the “Materials”) is provided solely for the selection and use of Xilinx products. To the maximum extent permitted by applicable law: (1) Materials are made available "AS IS" and with all faults, Xilinx hereby DISCLAIMS ALL WARRANTIES AND CONDITIONS, EXPRESS, IMPLIED, OR STATUTORY, INCLUDING BUT NOT LIMITED TO WARRANTIES OF MERCHANTABILITY, NON-INFRINGEMENT, OR FITNESS FOR ANY PARTICULAR PURPOSE; and (2) Xilinx shall not be liable (whether in contract or tort, including negligence, or under any other theory of liability) for any loss or damage of any kind or nature related to, arising under, or in connection with, the Materials (including your use of the Materials), including for any direct, indirect, special, incidental, or consequential loss or damage (including loss of data, profits, goodwill, or any type of loss or damage suffered as a result of any action brought by a third party) even if such damage or loss was reasonably foreseeable or Xilinx had been advised of the possibility of the same. Xilinx assumes no obligation to correct any errors contained in the Materials or to notify you of updates to the Materials or to product specifications. You may not reproduce, modify, distribute, or publicly display the Materials without prior written consent. Certain products are subject to the terms and conditions of Xilinx’s limited warranty, please refer to Xilinx’s Terms of Sale which can be viewed at <http://www.xilinx.com/legal.htm#tos>; IP cores may be subject to warranty and support terms contained in a license issued to you by Xilinx. Xilinx products are not designed or intended to be fail-safe or for use in any application requiring fail-safe performance; you assume sole risk and liability for use of Xilinx products in such critical applications, please refer to Xilinx’s Terms of Sale which can be viewed at <http://www.xilinx.com/legal.htm#tos>.